

## Silicone Thermal Pad / XK-P50

### Introduction

This series of products are resilient and with large deformation, suitable for large institutional design tolerances. Single or double layer structure, the double layer is reinforced with special ultra-thin fabric to increase resistance and workability of puncture, strip type, malformation designs. Self-adhesive and never recede. No corrosion to the copper surface, "environmentally friendly products".

### Features

Ultra conformable, "gel-like" modulus  
Designed for low-stress applications  
low hardness

### Applications

Telecommunications  
Computer, Between heat-generating semiconductor and a heat sink



	Unit	XK-P50	Method
Reinforcement Carrier		-	
Inherent Surface Tack (1-/2- sided)		2-side	
Color		Red	visual
Thickness	mm	0.3~3.0	ASTM D374
Specific Gravity	g/cm <sup>3</sup>	3.35	ASTM D792
Hardness	Asker C	25~30	JIS K7312
	Shore 00	45~55	ASTM D2240
Thermal impedance@0.5mm 14.5psi	°Cin <sup>2</sup> /W	0.21	ASTM D5470
Thermal Conductivity	W/mK	5.0	HOT DISK
Volume Resistivity	Ωcm	>10 <sup>13</sup>	ASTM D257
Breakdown Voltage	KV/mm	>10	ASTM D149
Dielectric Constant	1	8	ASTM D150
Application temperature	°C	-50~200	
Tensile strength	psi	12	ASTM D149
Elongation	%	40	ASTM D149
Siloxane Volatiles D4~D20	%	<0.005	GC-FID
Flammability	UL94	V-0	UL94